

• General Description

It combines trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Low $R_{DS(ON)}$ to minimize conductive loss
- High GOX reliability
- Low Thermal resistance

• Application

- BLDC Motor driver
- DC-DC
- Load switch

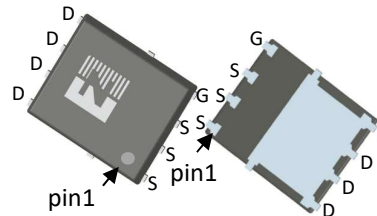
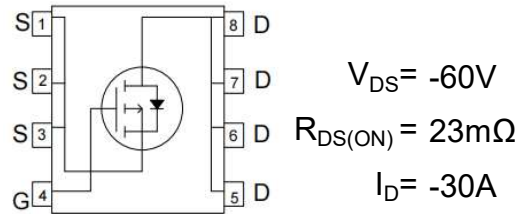
• Ordering Information:

Part NO.	ZM230P06N
Marking	ZM230P06
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• Absolute Maximum Ratings ($T_C=25^{\circ}C$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		-60	V
Gate-Source Voltage ^①	V_{GS}		±20	V
Continuous Drain Current	I_D	$T_C=25^{\circ}C$	-30	A
	I_D	$T_C=75^{\circ}C$	-28	A
	I_D	$T_C=100^{\circ}C$	-24	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu s$; $T_{mb} = 25^{\circ}C$;	-120	A
Total Power Dissipation	P_D	$T_C=25^{\circ}C$	83	W
Total Power Dissipation	P_D	$T_A=25^{\circ}C$	3.3	W
Operating Junction Temperature	T_J		-55 to +175	$^{\circ}C$
Storage Temperature	T_{STG}		-55 to +175	$^{\circ}C$
Single Pulse Avalanche Energy	E_{AS}	L=0.1mH, $V_{GS}=-10V$, $R_g=25\Omega$,	45	mJ
		L=0.5mH, $V_{GS}=-10V$, $R_g=25\Omega$,	94.5	mJ
ESD Level (HBM)			CLASS 2	

• Product Summary



DFN5*6



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	1.8	°C/W
Thermal resistance, junction-ambient ^②	R_{thJA}		-	45	°C/W
Soldering temperature	T_{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = -250\mu A$	-60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu A$	-1.3	-1.8	-2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS} = 0V, V_{DS} = -60V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = -10V, I_D = -15A$		23	34	m Ω
		$V_{GS} = -4.5V, I_D = -10A$		29	41	m Ω
Forward Transconductance	g_{FS}	$V_{DS} = -5V, I_{SD} = -10A$		20		S
Diode Forward Voltage	V_{FSD}	$V_{GS} = 0V, I_{SD} = -15A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f = 1MHz, V_{DS} = -25V$	-	3300	-	pF
Output capacitance	C_{oss}		-	148	-	
Reverse transfer capacitance	C_{rss}		-	96	-	
Gate Resistance	R_g	$f = 1MHz$	-	8		Ω
Total gate charge	Q_g	$V_{DD} = -15V, I_D = -10A, V_{GS} = -10V$	-	46	-	nC
	$Q_g(-4.5V)$		-	21	-	
Gate - Source charge	Q_{gs}		-	6.3	-	
Gate - Drain charge	Q_{gd}		-	8.6	-	
Turn-ON Delay time	$t_{D(on)}$		-	13	-	
Turn-ON Rise time	t_r	$V_{GS} = -10V, V_{DS} = -15V, R_G = 3.3\Omega, I_D = -10A$	-	21	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	87	-	ns
Turn-Off Fall time	t_f		-	34	-	ns
Reverse Recovery Time	t_{RR}		$V_{DD} = -20V, di_S/dt = 100A/\mu s, I_S = -20A$	-	66	-
Reverse Recovery Charge	Q_{RR}		-	263	-	nC

Fig.1 Gate-Charge Characteristics

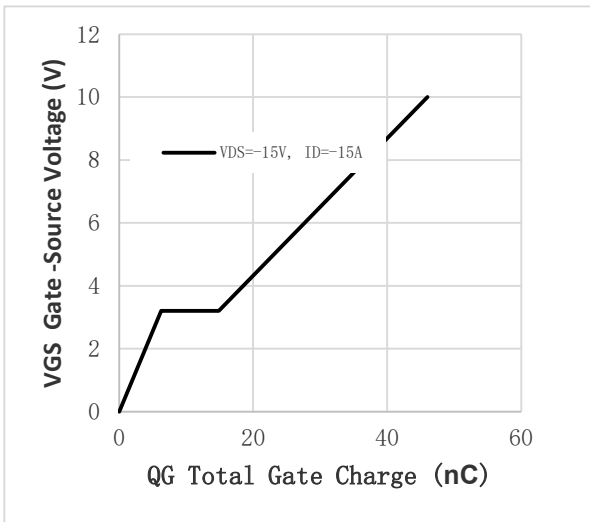


Fig.2 Capacitance Characteristics

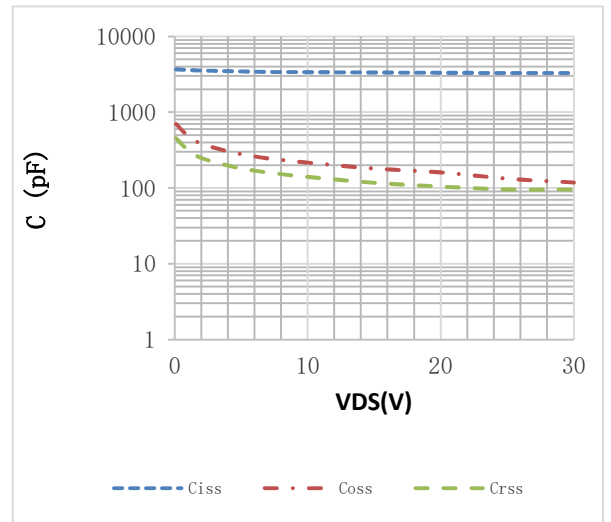


Fig.3 Power Dissipation

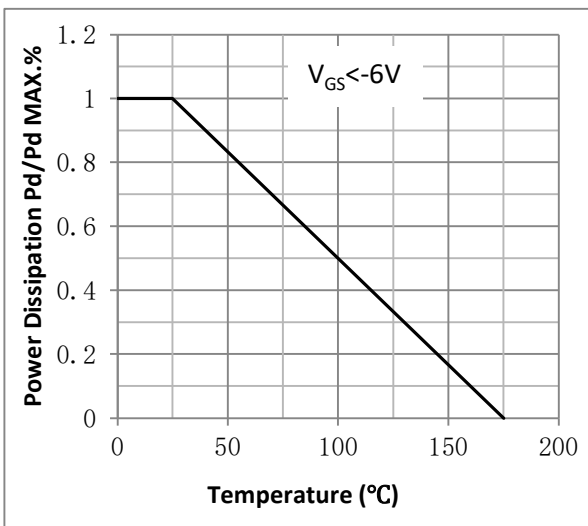


Fig.4 Typical output Characteristics

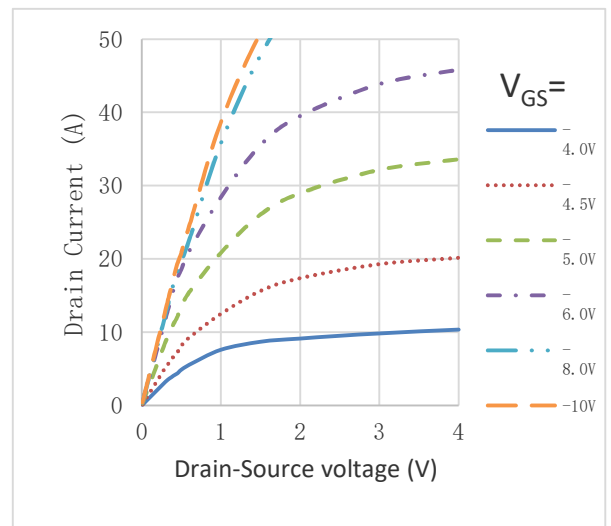


Fig.5 Threshold Voltage V.S Junction Temperature

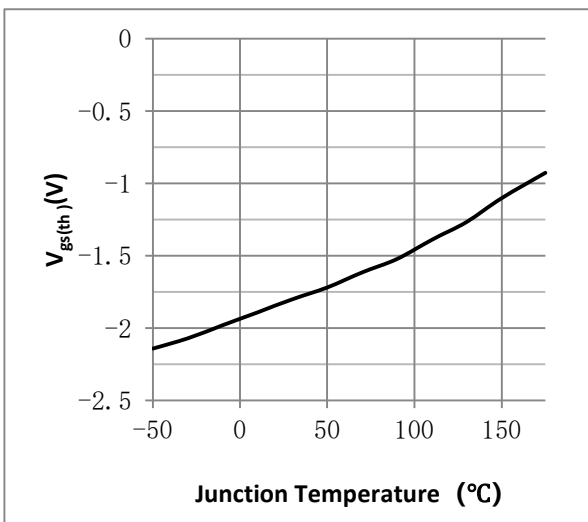


Fig.6 Resistance V.S Drain Current

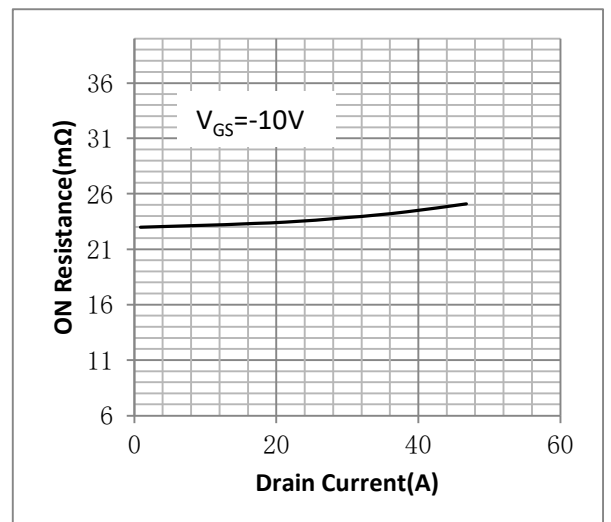


Fig.7 On-Resistance VS Gate Source Voltage

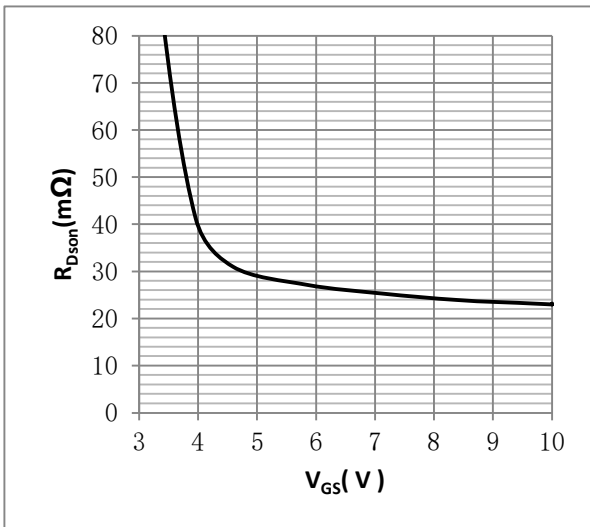


Fig.8 On-Resistance V.S Junction Temperature

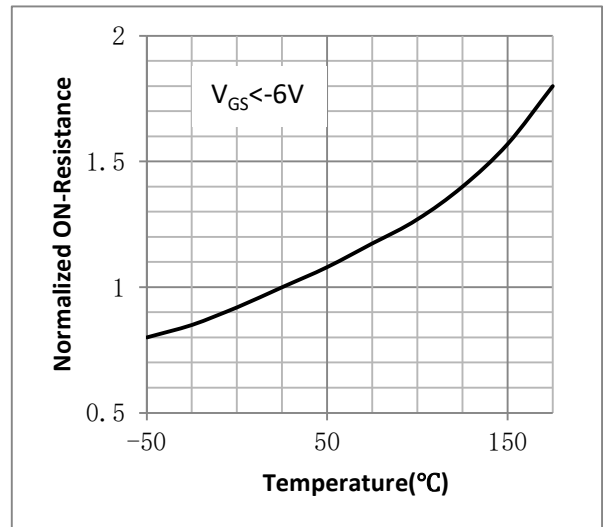


Figure 9. Diode Forward Voltage vs. Current

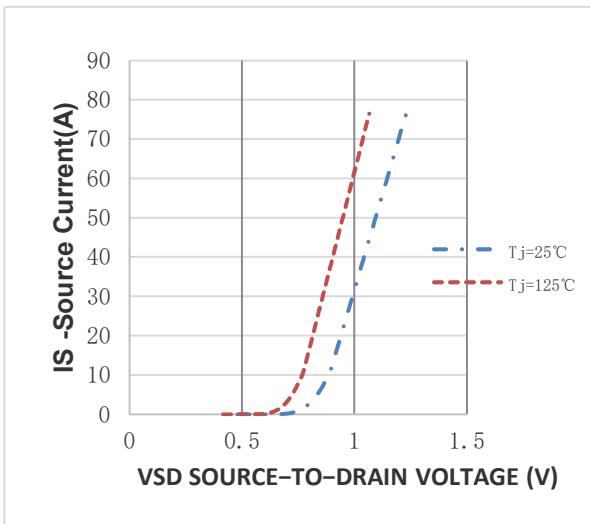


Figure 10. Transfer Characteristics

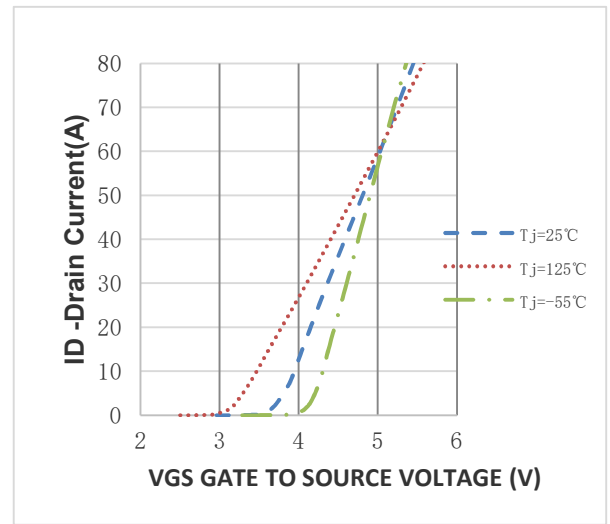


Fig.11 Safe Operating Area

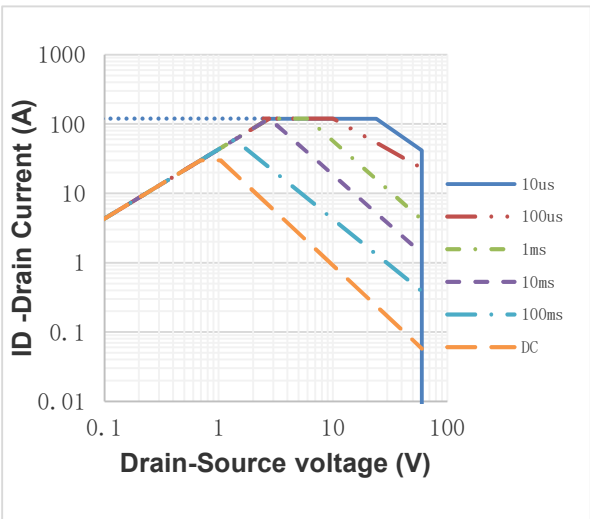
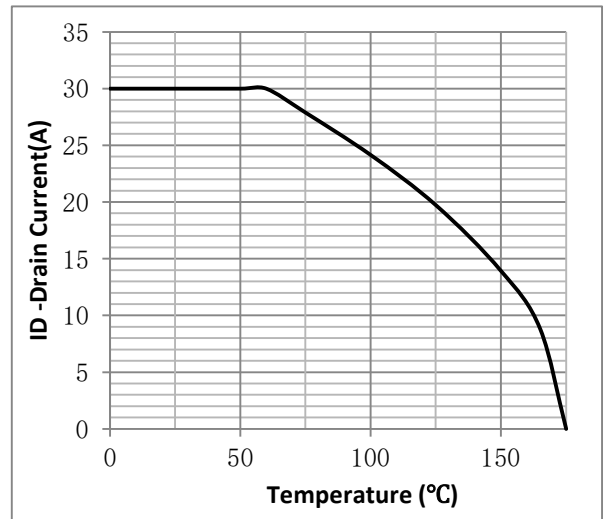
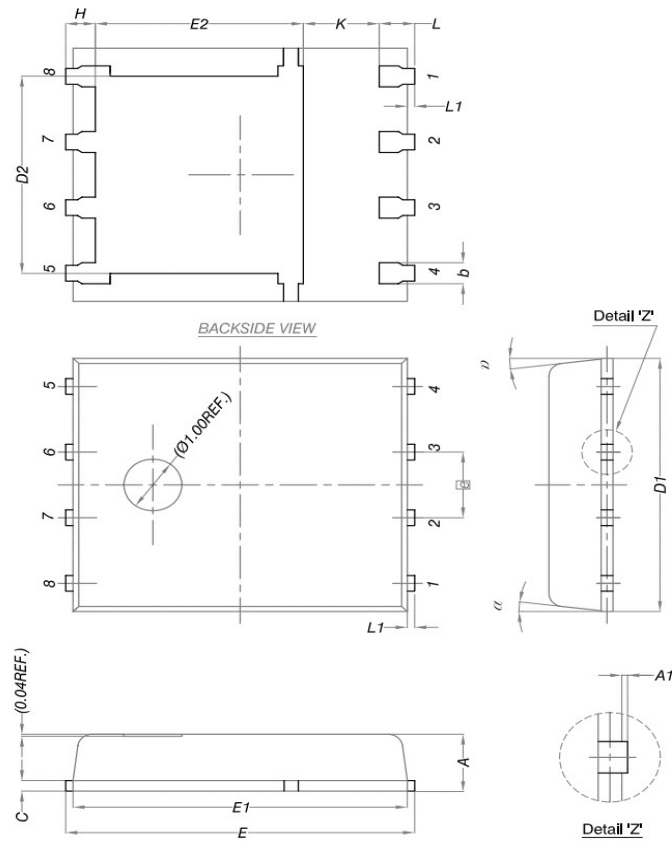


Fig.12 I_D vs. Case Temperature^③



•DFN5*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°

Note:

- ① Pulse : $V_{GS}=+20V/-20V$, Duty cycle=50%, $T_j=175^{\circ}C$, $t=1000$ hours; For DC , the following test conditions can be passed: $V_{GS}=-20V/+10V$, $T_j=175^{\circ}C$, $t=1000$ hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=-10V$.

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Revision History

Version	Date	Change
A	2021.12.3	NEW
B	2022.9.7	1.Add Reach,HF figure
C	2023.7.3	Modified the symbol figure